

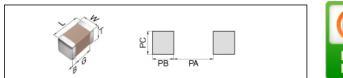
△TDK Multilayer Ceramic Chip Capacitors

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Creation Date: October 24, 2014

C3216X5R0J107M160AB (TDK item description : C3216X5R0J107MT****)

Applications Commercial Grade Feature General General (Up to 50V) C3216 [EIA CC1206] Series









Size		
Length(L)	3.20mm +0.30/-0.10mm	
Width(W)	1.60mm +0.30/-0.10mm	
Thickness(T)	1.60mm +0.30/-0.10mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)	1.00mm Min.	
Recommended Land Pattern(PA)	2.10 to 2.50mm (Flow Soldering) br />2.00 to 2.40mm (Reflow Soldering)	oldering
Recommended Land Pattern(PB)	1.10 to 1.30mm (Flow Soldering) 1.10 to 1.20mm (Reflow Soldering)	oldering
Recommended Land Pattern(PC)	1.00 to 1.30mm (Flow Soldering) < br />1.10 to 1.60mm (Reflow So	oldering
Recommended Slit Pattern(SD)		

Electrical Characteristics		
Capacitance	100uF +/-20%	
Rated Voltage	6.3Vdc	
Temperature Characteristic	X5R(+/-15%)	
Dissipation Factor	10% Max.	
Insulation Resistance	1MΩ Min.	

Other		
Soldering Method	Reflow, Flow	
AEC Q200	No	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	2000Pcs Min.	

[•]This PDF document was created based on the data listed on the TDK Corporation website.

[•]All specifications are subject to change without notice.

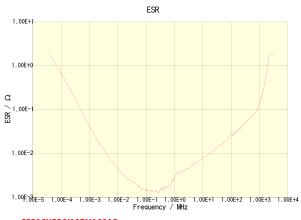
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Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)

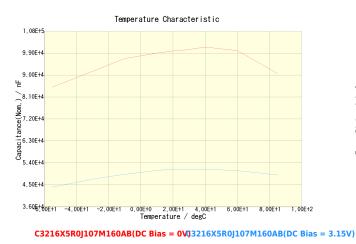


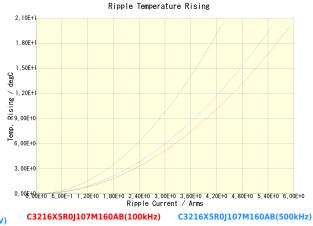


C3216X5R0J107M160AB









C3216X5R0J107M160AB(1MHz)

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